

34mm Half Bridge IGBT Module

$V_{CES} = 1700V$, $I_C = 150A$, $V_{CE(sat)} = 1.7V$

Features

- High Speed Trench / Field Stop IGBT
- Low $V_{CE(sat)}$
- Low Switching Losses
- $V_{CE(sat)}$ With Positive Temperature Coefficient



Applications

- Inverter
- Servo Drives
- Solar Applications
- UPS Systems



IGBT, Inverter Maximum Ratings

Parameter	Symbol	Condition	Value	Unit
Collector-emitter voltage	V_{CES}	$T_{vj}=25^{\circ}C$, $V_{GE}=0V$	1700	V
Continuous collector current	$I_{C\ nom}$	$T_C=100^{\circ}C$, $T_{vj\ max}=175^{\circ}C$	150	A
Repetitive peak collector current	I_{CRM}	$t_P=1ms$, $T_{vj}=25^{\circ}C$	300	A
Gate-emitter peak voltage	V_{GES}	$T_{vj}=25^{\circ}C$	± 20	V
Total power dissipation	P_{tot}	$T_C=25^{\circ}C$, $T_{vj\ max}=175^{\circ}C$	750	W

Characteristics Values

Parameter	Symbol	Conditions	Value			Unit	
			Min.	Typ.	Max.		
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C=150A$, $V_{GE}=15V$	$T_{vj}=25^{\circ}C$		1.7	2.1	V
			$T_{vj}=125^{\circ}C$		2.0		V
			$T_{vj}=150^{\circ}C$		2.1		V
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=3.1mA$, $V_{CE}=V_{GE}$	$T_{vj}=25^{\circ}C$	6.0	6.5	7.1	V
Gate charge	Q_G	$V_{GE}=-15V...+15V$		1.4			μC
Integrated gate resistor	$R_{G\ int}$	$T_{vj}=25^{\circ}C$		1.2			Ω
Input capacitance	C_{ies}	$T_{vj}=25^{\circ}C$, $f=100KHZ$, $V_{CE}=25V$, $V_{GE}=0V$		21.5			nF
Output capacitance	C_{oes}	$T_{vj}=25^{\circ}C$, $f=100KHZ$, $V_{CE}=25V$, $V_{GE}=0V$		0.65			nF

Reverse transfer capacitance	C_{res}	$T_{vj}=25^{\circ}C, f=100KHZ, V_{CE}=25V, V_{GE}=0V$		0.09		nF
Collector-emitter cut-off current	I_{CES}	$V_{CE}=1700V, V_{GE}=0V$	$T_{vj}=25^{\circ}C$		1	mA
Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$	$T_{vj}=25^{\circ}C$		100	nA
Turn-on delay time	$t_{d\ on}$	$I_C=150A, V_{CE}=900V, V_{GE}=-15V/+15V, R_G=5\Omega, \text{Inductive Load}$	$T_{vj}=25^{\circ}C$	128		ns
			$T_{vj}=125^{\circ}C$	136		ns
			$T_{vj}=150^{\circ}C$	139		ns
Rise time	t_r		$T_{vj}=25^{\circ}C$	57		ns
			$T_{vj}=125^{\circ}C$	64		ns
			$T_{vj}=150^{\circ}C$	69		ns
Turn-off delay time	$t_{d\ off}$		$T_{vj}=25^{\circ}C$	360		ns
			$T_{vj}=125^{\circ}C$	413		ns
			$T_{vj}=150^{\circ}C$	436		ns
Fall time	t_f	$T_{vj}=25^{\circ}C$	535		ns	
		$T_{vj}=125^{\circ}C$	744		ns	
		$T_{vj}=150^{\circ}C$	847		ns	
Turn-on energy loss per pulse	E_{on}	$T_{vj}=25^{\circ}C$	36.27		mJ	
		$T_{vj}=125^{\circ}C$	44.89		mJ	
		$T_{vj}=150^{\circ}C$	50.21		mJ	
Turn-off energy loss per pulse	E_{off}	$T_{vj}=25^{\circ}C$	34.48		mJ	
		$T_{vj}=125^{\circ}C$	44.15		mJ	
		$T_{vj}=150^{\circ}C$	48.06		mJ	
SC data	I_{SC}	$V_{GE}\leq 15V, V_{CE}=1000V, V_{CEmax}=V_{CES}-L_{sCE}\cdot di/dt, t_p\leq 8\mu s,$	$T_{vj}=25^{\circ}C$	640		A
		$V_{GE}\leq 15V, V_{CE}=1000V, V_{CEmax}=V_{CES}-L_{sCE}\cdot di/dt, t_p\leq 6\mu s,$	$T_{vj}=150^{\circ}C$	630		A
Thermal resistance, junction to case	R_{thJC}	per IGBT			0.195	K/W
Temperature under switching conditions	$T_{vj\ op}$		-40		175	$^{\circ}C$

Diode, Inverter Maximum Ratings

Parameter	Symbol	Conditions	Value	Unit	
Repetitive peak reverse voltage	V_{RRM}	$T_{vj}=25^{\circ}C$	1700	V	
Continuous forward current	I_F	$T_C=100^{\circ}C, T_{vj\ max}=175^{\circ}C$	150	A	
Repetitive peak forward current	I_{FRM}	$t_p=1ms$	300	A	
I^2t -value	I^2t	$t_p=10ms, \sin 180^{\circ}$	$T_{vj}=125^{\circ}C$	5400	A^2s

Characteristics Values

Parameter	Symbol	Conditions	Values			Units
			Min.	Typ.	Max.	
Forward voltage	V_F	$I_F=150A, V_{GE}=0V$	$T_{vj}=25^{\circ}C$	1.7		V
			$T_{vj}=125^{\circ}C$	1.9		V
			$T_{vj}=150^{\circ}C$	1.95		V
Peak reverse recovery current	I_{rr}		$T_{vj}=25^{\circ}C$	123		A
			$T_{vj}=125^{\circ}C$	136		A
			$T_{vj}=150^{\circ}C$	141		A
Recovered charge	Q_{rr}	$I_F=150A, V_R=900V, V_{GE}=-15V, -diF/dt=2000A/\mu s (T_{vj}=150^{\circ}C)$	$T_{vj}=25^{\circ}C$	38.6		μC
			$T_{vj}=125^{\circ}C$	59.6		μC
			$T_{vj}=150^{\circ}C$	72.5		μC
Reverse recovery energy	E_{rec}		$T_{vj}=25^{\circ}C$	21.36		mJ
			$T_{vj}=125^{\circ}C$	35.71		mJ
			$T_{vj}=150^{\circ}C$	44.47		mJ
Thermal resistance, junction to case	R_{thJC}	per FRD			0.257	K/W
Temperature under switching conditions	$T_{vj op}$		-40		175	$^{\circ}C$

Module Characteristics Values

Parameter	Symbol	Conditions	Values			Units
			Min.	Typ.	Max.	
Isolation test voltage	V_{ISOL}	RMS, f=50Hz, t=1min		4		kV
Internal isolation	-		Al_2O_3			-
Maximum junction temperature	$T_{vj max}$				175	$^{\circ}C$
Temperature under switching conditions	$T_{vj op}$		-40		175	$^{\circ}C$
Storage temperature	T_{stg}		-40		125	$^{\circ}C$
Mounting torque for module mounting	M		3	-	6	N·m
Weight	G			149		g

Typical Characteristics

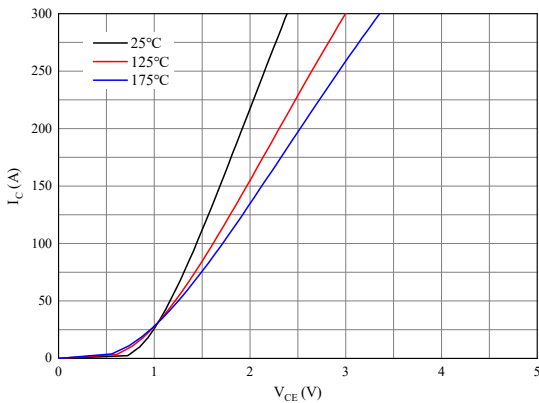


Fig 1. Typical output characteristics ($V_{GE}=15V$)

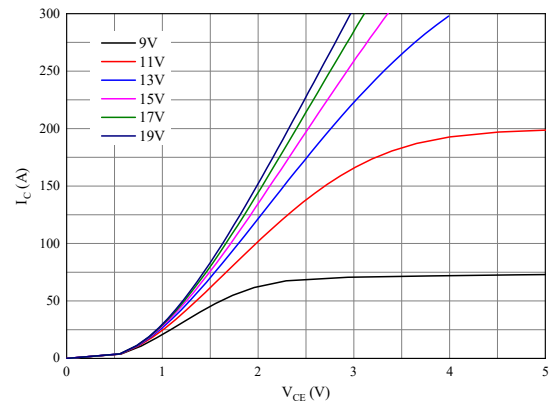


Fig 2. Typical output characteristics ($T_{vj}=150^{\circ}C$)

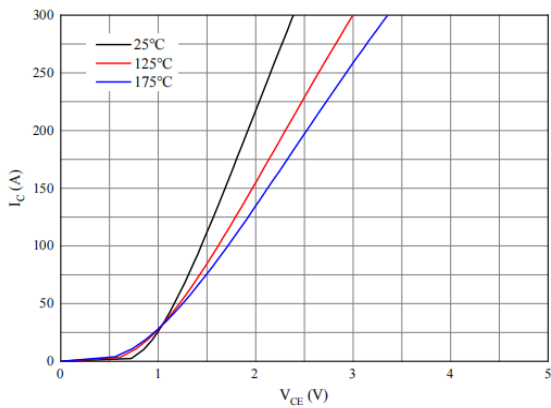


Fig 3. Typical transfer characteristics ($V_{CE}=20V$)

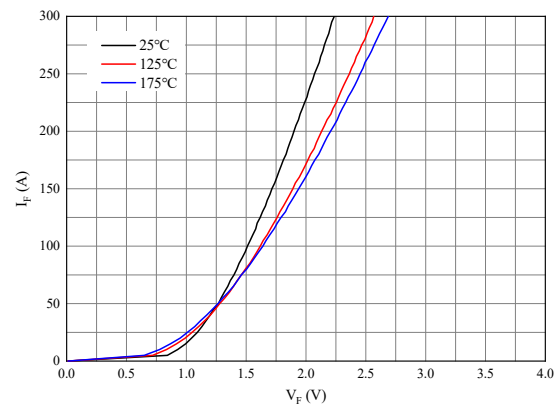


Fig 4. Forward characteristics of Diode

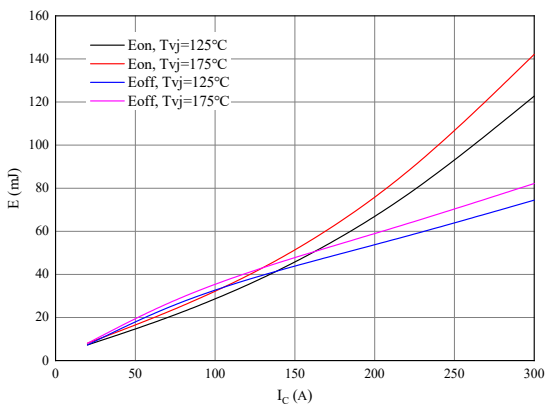


Fig 5. Switching losses of IGBT, Inverter
 $V_{GE}=\pm 15V$, $R_{Gon}=R_{Goff}=5\Omega$, $V_{CE}=900V$

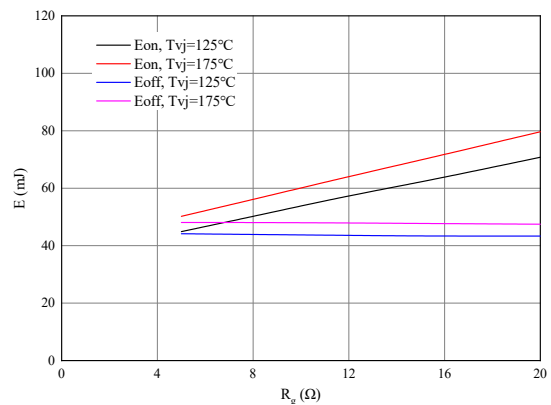


Fig 6. Switching losses of IGBT, Inverter
 $V_{GE}=\pm 15V$, $I_C=75A$, $V_{CE}=900V$

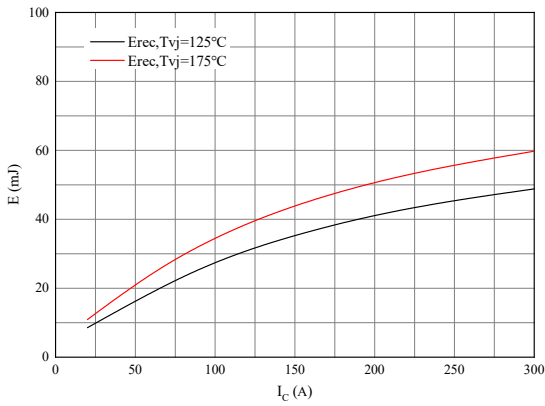


Fig 7. Switching losses of Diode
 $R_{Gon}=R_{Goff}=5\Omega$, $V_{CE}=900\text{V}$

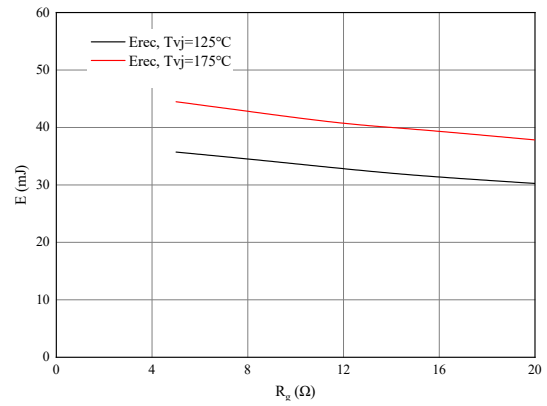


Fig 8. Switching losses of Diode
 $I_F=75\text{A}$, $V_{CE}=900\text{V}$

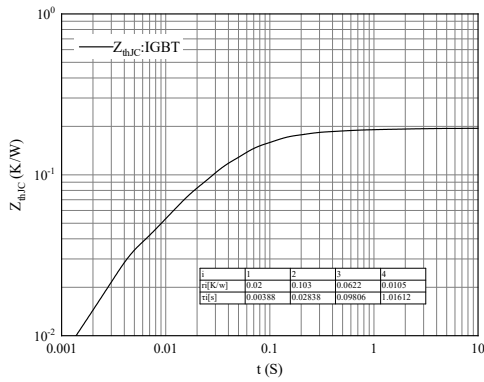


Fig 9. Transient thermal impedance IGBT, Inverter, $Z_{thJC}=f(t)$

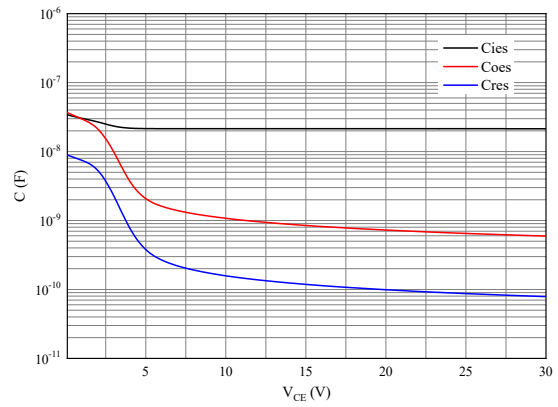


Fig 10. Capacitance characteristics

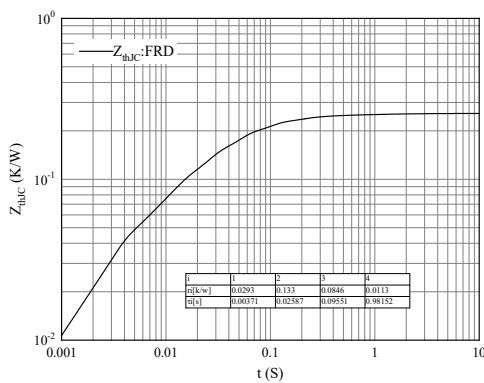
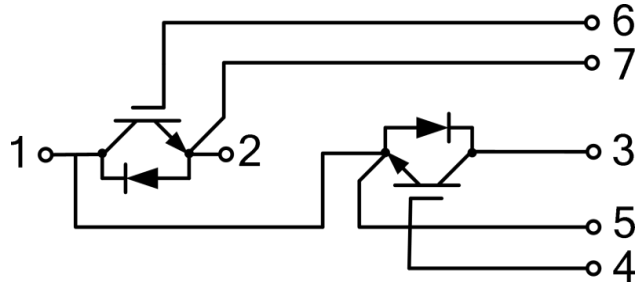
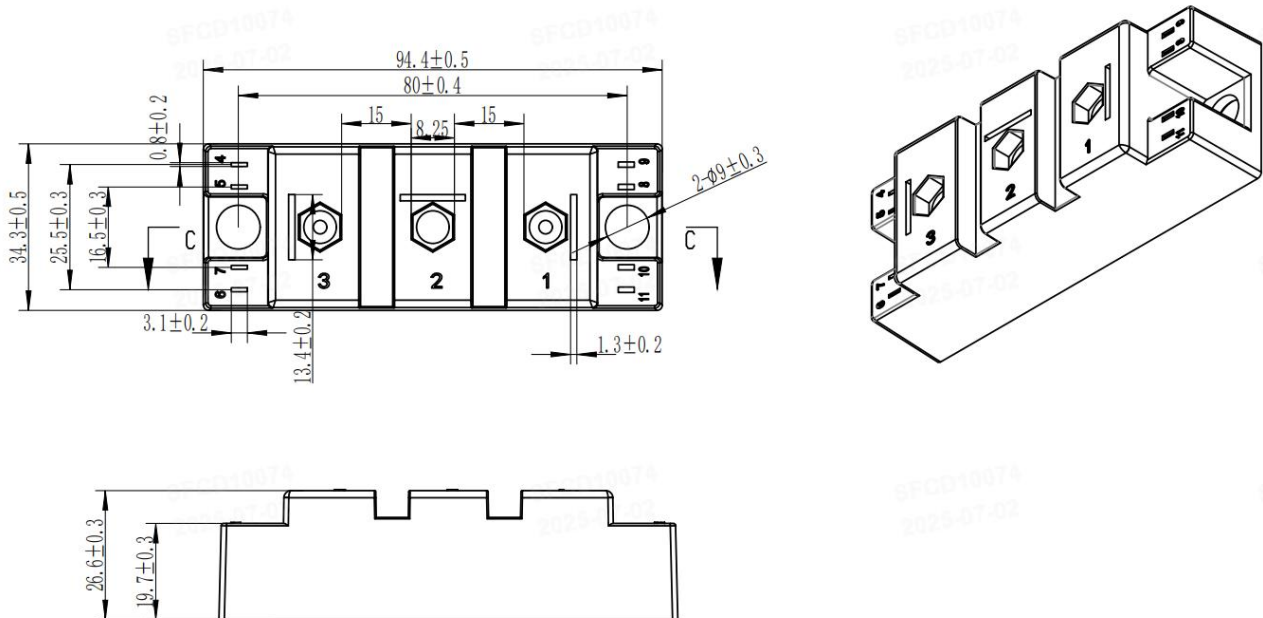


Fig 11. Transient thermal impedance FRD, Inverter, $Z_{thJC}=f(t)$

Circuit Diagram



Package Outlines (Unit:mm)



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